# **SPECIFICATIONS**

CUSTOMER	•
COSICIMEN	•

# SAMPLE CODE : GFG128064A-FPGE-01

# DRAWING NO. : \_\_\_\_\_

# DATE : <u>2009.03.02</u>

# CERTIFICATION : ROHS

Customer Sign	Sales Sign	Approved By	Prepared By

### **Revision Record**

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#### **CONTENTS**

1.	SCO	PE	 4
2.	PRO	DUCT SPECIFICATIONS	 4
	2.1	General	 4
	2.2	Mechanical Characteristics	 4
	2.3	Absolute Maximum Ratings	 5
	2.4	Electrical Characteristics	 5
	2.5	Optical Characteristics Absolute maximum ratings	 5
	2.6	Optical Characteristics	 6
	2.7	LED Back-light Characteristics	 7
3.	REL	IABILITY	 8
4.	OPE	RATING INSTRUCTIONS	 9

	4.1	Input signal Function	 9
	4.2	Voltage Generator Circuit	 10
	4.3	Timing Diagram	 13
5.	NOT	TES	 16
6.	OPE	RATION PRECAUTIONS	 16
7.	LCN	1 DIMENSIONS	 17

### 1. SCOPE

This specification covers the engineering requirements for the GFG128064A-FPGE-01 liquid crystal module.

### 2. PRODUCT SPECIFICATIONS

- 2.1 General
  - 128 \$64 dot matrix LCD
  - FSTN , Positive mode LCD panel
  - Transflective, Wide temperature type
  - 6 o'clock
  - Back light: Edge LED (BLUE)
  - Multiplexing driving : 1/65duty, 1/9bias
  - Conteroller IC UC1601

#### 2.2 Mechanical Characteristics

Item	Characteristic	
Dot configuration	128 �64	
Dot dimensions(mm)	0.334 \$0.403	
Dot spacing (mm)	0.364 \$0.433	
Module dimensions (Horizontal Vertical &Thickness, mm)	56.6 \$44.2 \$7.65 max.	
Viewing area (Horizontal ♦ Vertical, mm)	50.6 \$31	2.3 Absolute Maximum
Active area (Horizontal &Vertical, mm)	46.562 \$\$27.682	Ratings (Without LED

back-light)

Characteristic	Symbol	Unit	Value
Operating Voltage (logic)	V <sub>DD</sub>	V	-0.3 to +4.0
Input Voltage	V <sub>IN</sub>	V	-0.3 to V <sub>DD</sub> +0.3

Note 1: Referenced to V<sub>ss</sub>=0V

### 2.4 Electrical Characteristics (Without LED back-light)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Vdd	Supply for digital circuit		2.4		3.3	V
V <sub>DD2/3</sub>	Supply for bias & pump		2.4		3.3	V
V <sub>LCD</sub>	Charge pump output	V <sub>DD2/3</sub> ≥ 2.4V, 25 <sup>0</sup> C			11.5	V
VD	LCD data voltage	$V_{DD2/3} \ge 2.4V, 25^{O}C$	0.80		1.32	V
Vil	Input logic LOW				0.2V <sub>DD</sub>	V
VIH	Input logic HIGH		0.8V <sub>DD</sub>			V
Vol	Output logic LOW				0.2Vpp	V
Voн	Output logic HIGH		0.8Vdd			V
կլ	Input leakage current				1.5	μA
R <sub>0(SEG)</sub>	SEG output impedance	V <sub>LCD</sub> = 11V		2	3	kΩ
R0(COM)	COM output impedance	V <sub>LCD</sub> = 11V		2	3	kΩ
F <sub>FR</sub>	Average Frame Rate	LC[3] = 0b	66	76		Hz

### 2.5 Optical Characteristics Absolute maximum ratings

Item	Symbol	Rating	Unit
------	--------	--------	------

Operating temperature range	Тор	-20~70	<b>⊕</b> C
Storage temperature range	Tst	-30~80	<b>⊕</b> C

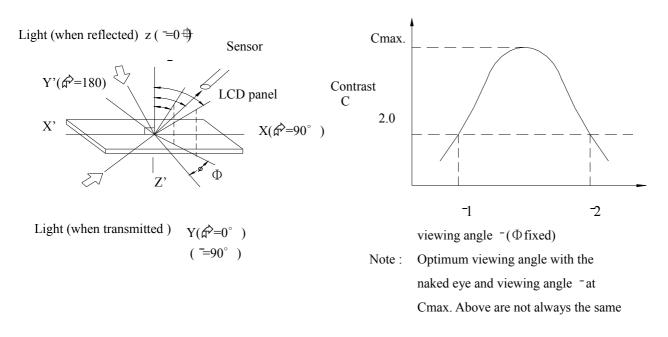
### 2.6 Optical Characteristics

	1/65 duty, 1/9bias, Vop=10.2V, Ta=25°C					
Item	Symbol	Conditions	Min.	Тур.	Max	Reference
Driving voltage	Vop=VDD-VO			10.2		
Viewing angle	_	C≥2.0,¢>=0€€	30⊕			Notes 1 & 2
Contrast	С	-=5⊕☆=0⊕	3.0			Note 3
Response time(rise)	ton	-=5⊕☆=0⊕			198ms	Note 4
Response time(fall)	toff	-=5⊕☆=0⊕			176ms	Note 4

Note 1: Definition of angles  $\neg$  and  $\cancel{P}$ 

Note 2: Definition of viewing angles  $\neg 1$  and  $\cancel{P}^2$ 

Note 4: Definition of response time

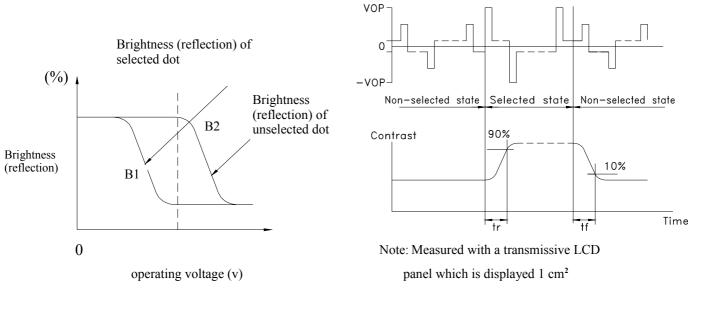


#### Note 3: Definition of contrast C

Brightness (reflection) of unselected dot (B2)

C =

Brightness (reflection) of selected dot (B1)



V OPR : Operating voltage	$f_{FRM}$ : Frame frequency			
t ON : Response time (rise)	t <sub>OFF</sub> : Response time (fall)			

at

### 2.7 LED Back-light Characteristics

#### 2.7.1 Electrical / optical specifications

$Ta = 25 \neq \mathbb{C}$							
Item	Symbol	Condition	Min.	Тур.	Max.	Unit	
Forward voltage	$V_{\rm f}$	If=40mA, BLUE	2.9	3.2	3.6	V	Note: * Measured
LED *Luminous Intensity	I <sub>v</sub>	If=40mA, BLUE		120		Cd/m2	the bare LED back
Reverse Current	I <sub>R</sub>	VR=5V, BLUE			0.1	mA	light unit.

#### 2.7.2 LED Maximum Operating Range

Item	Symbol	BLUE	Unit
Power Dissipation	P <sub>AD</sub>	144	mW
Forward Current	$I_F$	40	mA
Reverse Voltage	$\mathbf{V}_{R}$	5	V

### **3. RELIABILITY**

### 3.1 Reliability

ity		
Test item	Test condition	Evaluation and assessment
Operation at high temperature and humidity	40 °C ⊕2 °C 90%RH for 500hours	No abnormalities in functions* and appearance**
Operation at high temperature	60 °C ⊕2 °C for 500 hours	No abnormalities in functions* and appearance**
Heat shock	-20 ↔~ +60 °C Left for 1 hour at each temperature, transition time 5 min, repeated 10times	No abnormalities in functions* and appearance**
Low temperature	-20 € °C for 500 hours	No abnormalities in functions* and appearance**
Vibration	Sweep for 1 min at 10 Hz, 55Hz, 10Hz, amplitude 1.5mm 2 hrs each in the X,Y and Z directions	No abnormalities in functions* and appearance**
Drop shock	Dropped onto a board from a height of 10cm	No abnormalities in functions* and appearance**

\* Dissipation current, contrast and display functions

\*\* Polarizing filter deterioration, other appearance defects

3.2 Liquid crystal panel service life

100,000 hours minimum at 25 °C +10 °C

- 3.3 definition of panel service life
  - Contrast becomes 30% of initial value
  - Current consumption becomes three times higher than initial value
  - Remarkable alignment deterioration occurs in LCD cell layer
  - Unusual operation occurs in display functions

### 4. OPERATING INSTRUCTIONS

#### 4.1 Input signal Function

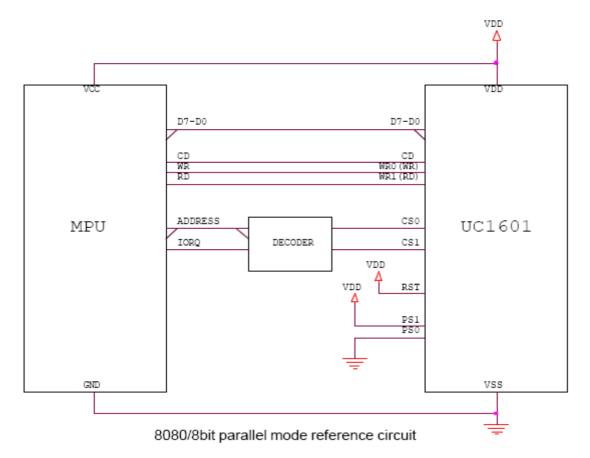
<b>1</b>	t signai rui							
Pin No	Symbol	I/O			Function			
1~4	NC	-	No Conr	nection.				
5	VLCD	PWR	Main LC	D power supply.				
6	<b>V</b> B0+	PWR	LCD Bia	s Voltages. The	se are the voltag	ge sources to provide		
7	<b>V</b> B0-	PWR	SEG driv	ving currents. Th	ese voltages ar	e generated internally.		
8	<b>V</b> B1-	PWR	Connect	capacitors of C	BX value betwee	n V <sup>BX+</sup> and V <sup>BX-</sup> .		
9	<b>V</b> B1+	PWR						
10	VSS	PWR	Power G	iround.				
11	VDD	PWR	Power s	upply terminal V	CC.			
12	BM1	I	Bus mod	de: "HL": 8080	"HH": 6800			
13	BM0		BM[1:0] "LH": S9 "LL": S8					
14	DB7	I/O	Bi-directional bus for both serial and parallel host interfaces.					
15	DB6	I/O	In serial	modes, connect	DB0 to SCK, DE	33 to SDA.		
16	DB5	I/O		BM=1x	BM=0x	]		
17	DB4	I/O	D0	(Parallel) D0	(Serial) SCK	-		
18	DB3/SDA	I/O	D0	D0 D1	SUK			
19	DB2	I/O	D2	D2				
20	DB1	I/O	D3 D4	D3 D4	SDA			
21	DB0/SCK	I/O	D5	D5				
			D6 D7	D6 D7	-			
					-			
22	WR1			controls the rea	-			
23	WR0	I				details. The meaning		
			-			rface is in the 6800		
						, these two pins are		
			not used	l and can be con	nected to Vss.			
24	CD	I	Select th	Select the incoming command if it is a control instruction or				
			•		s not used in S9	mode, connect it to		
				Vdd or Vss.				
			" L": co	ntrol instruction	"H": display d	ata		
25	RST		When R	ST="L", all contr	ol registers are	re-initialized by their		

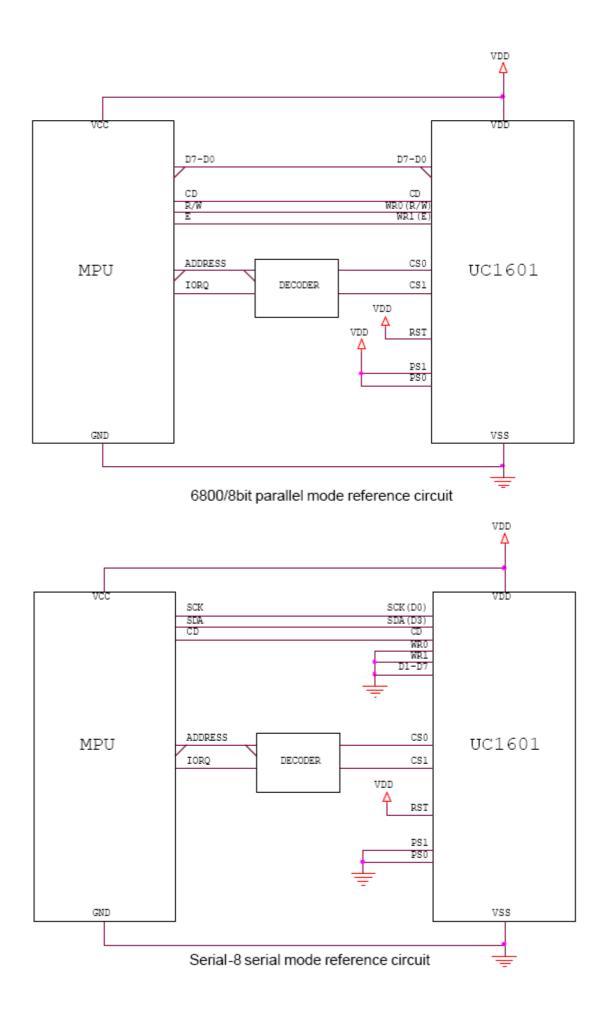
			default states.
26	/CS0	I	Chip Select or Chip Address. In parallel mode and S8 mode,
			chip is selected when /CS0="L". When the chip is not
			selected, DB[7:0] will be high impedance.
27~30	NC	-	No Connection.

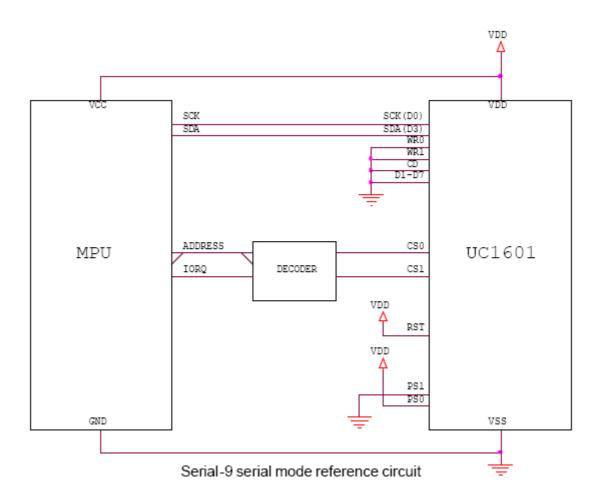
В	us Type	8080	6800	SPI (S8)	SPI (S9)	
(0	BM[1:0]	10b	11b	00b	01b	
Pins	CS[1:0]		Chip	Select –		
Data F	CD		Control/Data			
& Da	WR0	WR	R/W	-	_	
Control 8	WR1	RD	EN	-	_	
Son	Access	Read	Read/Write		e Only	
0	D[7:0]	8-bit bus	(Tri-state)	D0=SCK	, D3=SDA	

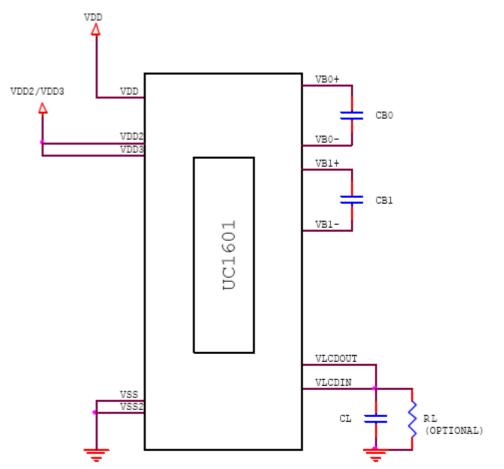
\* Connect unused control pins and data bus pins to V<sub>DD</sub> or V<sub>SS</sub>

### 4.2 Voltage Generator Circuit





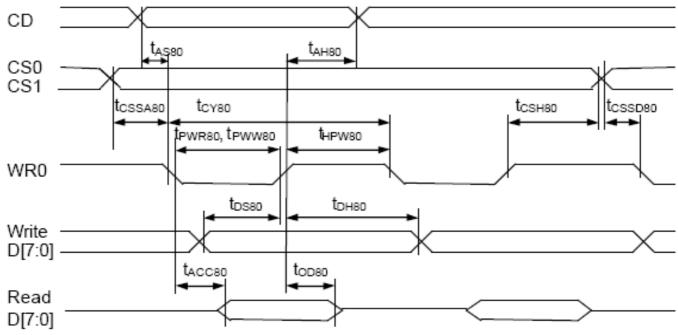




#### Note

- Recommended component values:
  - CB: 100x~200x LCD load capacitance or 1.0uF (2V), whichever is higher.
  - CL: 10nF ~ 30nF (25V) is appropriate for most applications.
  - RL: 10MQ. Acts as a draining circuit when the pow er is abnormally shut down.

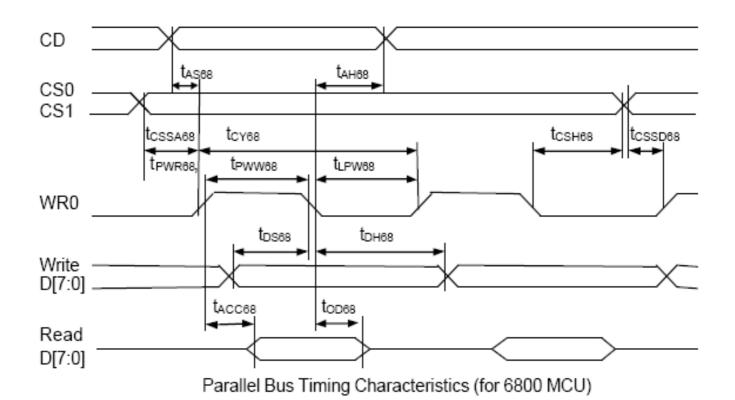
#### 4.3 Timing Diagram



Parallel Bus Timing Characteristics (for 8080 MCU)

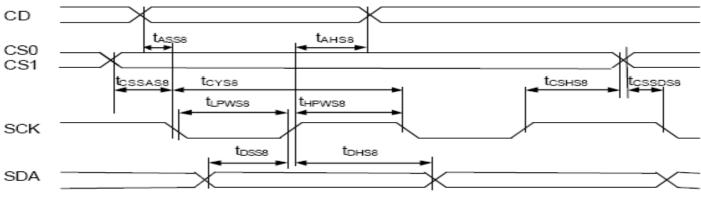
	V	T 001	
1750 6	Van < 3 3 V	12 3010 4	85 (1)
$V_{2,J}V \leq$	VDD ~ J.JV.	1a – - JU IU -	00 01
(		Ta= -30 to +	,

Symbol	Signal	Description	Condition	Min.	Max.	Units
tase0	CD	Address setup time		0	-	nS
tанво	CD	Address hold time		40		
t <sub>CY80</sub>		System cycle time		135	-	nS
t <sub>PWR80</sub>	WR1	Pulse width (read)		65	-	nS
t <sub>PWW80</sub>	WR0	Pulse width (write)		65	-	nS
t <sub>HPW80</sub>	WR0, WR1	High pulse width		65	-	nS
toseo	D0~D7	Data setup time		30	-	nS
t <sub>DH80</sub>	00~07	Data hold time		20		
t <sub>ACC80</sub>		Read access time	C <sub>L</sub> = 100pF	-	50	nS
topso		Output disable time		10	50	
tcssab0				10		nS
t <sub>CSSD80</sub>	CS1/CS0	Chip select setup time		10		
t <sub>CSH80</sub>				20		



(2.5V ≤ V<sub>DD</sub> < 3.3V, Ta= -30 to +85°C)

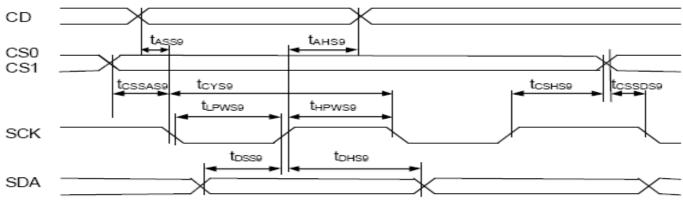
Symbol	Signal	Description	Condition	Min.	Max.	Units
tasee tahee	CD	Address setup time Address hold time		0 40	-	nS
t <sub>CY68</sub>		System cycle time		135	-	nS
t <sub>PWR68</sub>	WR1	Pulse width (read)		65	-	nS
t <sub>PWW68</sub>		Pulse width (write)		65	-	nS
tlpw68		Low pulse width		65	-	nS
tosee tohee	D0~D7	Data setup time Data hold time		30 15	-	nS
tacces t <sub>OD68</sub>		Read access time Output disable time	C∟ = 100pF	- 10	50 50	nS
Tcssabb T <sub>cssdbb</sub> T <sub>cshbb</sub>	CS1/CS0	Chip select setup time		10 10 20		nS



Serial Bus Timing Characteristics (for S8)

(2.5V ≤ V<sub>DD</sub> < 3.3V, Ta= -30 to +85°C)

Symbol	Signal	Description	Condition	Min.	Max.	Units
t <sub>ASS8</sub>	CD	Address setup time		0	-	nS
t <sub>AHS8</sub>	CD	Address hold time		40	-	nS
t <sub>CYS8</sub>		System cycle time		135	-	nS
t <sub>LPWS8</sub>	SCK	Low pulse width		65	-	nS
t <sub>HPWS8</sub>		High pulse width		65	-	nS
tosse tonse	SDA	Data setup time Data hold time		30 15	-	nS
tcssasa tcssdsa tcsHsa	CS1/CS0	Chip select setup time		10 10 20		nS



Serial Bus Timing Characteristics (for S9)

(2.5V ≤ V<sub>DD</sub> < 3.3V, Ta= -30 to +85°C)

Symbol	Signal	Description	Condition	Min.	Max.	Units
tasse	CD	Address setup time		0	-	nS
t <sub>AHS9</sub>	00	Address hold time		40	-	nS
t <sub>ovse</sub>		System cycle time		135	-	nS
t <sub>LPWS9</sub>	SCK	Low pulse width		65	-	nS
t <sub>HPWS9</sub>		High pulse width		65	-	nS
tosse	SDA	Data setup time		30	-	nS
t <sub>DHS9</sub>	ODA	Data hold time		15		
tcssase tcssdse	CS1/CS0	Chip select setup time		10 10		nS
tcsHS9				20		

### 5. NOTES

Safety PAGE 15/17 • If the LCD panel breaks, be careful not to get the liquid crystal in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and plenty of water.

#### <u>Handling</u>

- Avoid static electricity as this can damage the CMOS LSI.
- The LCD panel is plate glass; do not hit or crush it.
- Do not remove the panel or frame from the module.
- The polarizing plate of the display is very fragile; handle it very carefully

#### Mounting and Design

- Mount the module by using the specified mounting part and holes.
- To protect the module from external pressure, leave a small gap by placing transparent plates (e.g. acrylic or glass ) on the display surface, frame, and polarizing plate
- Design the system so that no input signal is given unless the power-supply voltage is applied.
- Keep the module dry. Avoid condensation, otherwise the transparent electrodes may break.

#### Storage

- Store the module in a dark place where the temperature is 25 °C +10 °C and the humidity below 65% RH.
- Do not store the module near organic solvents or corrosive gases.
- Do not crush, shake, or jolt the module (including accessories).

#### Cleaning

- Do not wipe the polarizing plate with a dry cloth, as it may scratch the surface.
- Wipe the module gently with soft cloth soaked with a petroleum benzine.
- Do not use ketonic solvents (ketone and acetoe) or aromatic solvents (toluene and xylene), as they may damage the polarizing plate.

## 6. OPERATION PRECAUTIONS

Any changes that need to be made in this specification or any problems arising from it will be dealt with quickly by discussion between both companies.

### 7. LCM Dimension

